

ABSTRACT

Disclosed is a film-form adhesive for adhering a semiconductor element to a support member for mounting the semiconductor element. This film-form adhesive contains an acrylic rubber. The acrylic rubber satisfies either the following condition (i) or condition (ii).

Condition (i): The acrylic rubber has a constituent unit derived from acrylonitrile and has a glass transition temperature (T_g) of higher than 12°C.

Condition (ii): The acrylic rubber does not have a constituent unit derived from acrylonitrile and has a glass transition temperature (T_g) of 0°C or higher.

Fig. 1